AUTOMATIC TWIN SPINDLE DICING SAWS

7930 Duo

For high UPH for large and multi panels

Features & Benefits

- Up to 12" X 10" chuck
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution

Workpiece Size		12" × 10" or Ø 12"
Spindle		Two facing 1.8 kW or 2.2 kW, max. 60,000 rpm
Blade Size		2" - 3"
Y1 / Y2 Axis	Control Resolution Cumulative Accuracy Indexing Accuracy	Linear encoder for each Y axis 0.1 µm 1.5 µm 1.0 µm
X Axis		Air Slide
Z1 / Z2 Axis	Resolution Repeatability Max. Stroke	0.2 µm 1.0 µm 30 mm (for 2.188" blade OD)
Θ Axis	Repeatability Stroke	4 arc-sec 380°
Utilities	Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm Weight	875 X 975 X 1450 900 kg

Materials:

Silicon wafers / discrete devices | Silicon carbide (SiC) | MEMS | SAW devices | Glass wafer | Packaging (QFN, LED…)

AUTOMATIC SINGLE SPINDLE DICING SAWS

7122

2" Spindle

Most flexible system

Features & Benefits

- Support 2"-3" blade O.D.
- 'X' axis air bearing for smooth motion and super cut quality
- Automation with high resolution optics
- Multi panel dicing
- Custom process solution
- Fast & simple blade change with a locking spindle shaft

Workpiece Size		Ø 8"
Spindle		60K rpm / 1.8 kW or 2.2KW
Blade Size		2" – 3"
Y Axis	Control Resolution Cumulative Accuracy Indexing Accuracy	Linear encoder 0.1 µm 1.5 µm 1.0 µm
X Axis		Air Slide
Z Axis	Resolution Repeatability	0.2 µm 1.0 µm
Θ Axis	Repeatability Stroke	4 arc-sec 380°
Utilities	Electrical	200-240 VAC, 50/60 Hz, single phase
Dimensions	(W x D x H) mm Weight	965 × 1300 × 1600 900 kg

Materials:

Glass | PZT | LED & LED on PCB Packages | Sensors & MEMS | Opto-electronic Components | IC Wafers | Automotive Sensors Ceramic Substrates & Capacitors | Glass on Silicon | LTCC | SAW Filters | Package Singulation (BGA, QFN)